

# **NPN & PNP General-Purpose Amplifier**

# **FMB3946**

#### Description

This complementary device is designed for use as a general–purpose amplifier and switch. The useful dynamic range extends to 100 mA as a switch and 100 MHz as an amplifier.

## **ABSOLUTE MAXIMUM RATINGS (Note 1)**

(T<sub>A</sub> = 25°C, unless otherwise noted)

Symbol	Parameter	Value	Unit	
V <sub>CEO</sub>	Collector - Emitter Voltage	40	V	
V <sub>CBO</sub>	Collector - Base Voltage	40		
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V	
I <sub>C</sub>	Collector Current – Continuous	200	mA	
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range	-55 to +150	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- These ratings are based on a maximum junction temperature of 150°C.
- 2. These are steady-state limits. **onsemi** should be consulted on applications involving pulsed or low-duty cycle operations.
- 3. All voltages (V) and currents (A) are negative polarity for PNP transistors.
- 4. These ratings are limiting values above which serviceability of any semiconductor advice may be impaired.

#### THERMAL CHARACTERISTICS (Note 5)

 $(T_A = 25^{\circ}C, \text{ unless otherwise noted})$ 

Symbol	Parameter	Max	Unit
P <sub>D</sub>	Power Dissipation	700	mW
	Derate Above 25°C	5.6	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction–to–Ambient	180	°C/W

5. PCB size: FR-4 76 x 114 x 0.6T mm<sup>3</sup> (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.



TSOT23 6-Lead CASE 419BL

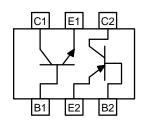
#### MARKING DIAGRAM



002 = Specific Device Code

= Date Code

#### INTERNAL CONNECTION



TRANSISTOR TYPE					
C1 B1 E1 NPN					
C2 B2 E2 PNP					

# ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
FMB3946	TSOT23-6 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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### FMB3946

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted) (Note 6)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
OFF CHAR	ACTERISTICS		•			
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	$I_C = 10 \text{ mA}, I_B = 0$	40	_	-	V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10 \mu A, I_E = 0$	40	_	-	V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10 \mu A, I_C = 0$	5.0	_	-	V
I <sub>CBO</sub>	Collector Cut-Off Current	V <sub>CB</sub> = 30 V, I <sub>E</sub> = 0	_	_	50	nA
I <sub>EBO</sub>	Emitter Cut-Off Current	$V_{EB} = 4.0 \text{ V}, I_{C} = 0$	_	_	50	nA
ON CHARA	CTERISTICS		•			
h <sub>FE</sub>	DC Current Gain	$I_C = 100 \mu A, V_{CE} = 1.0 V$	40	_	_	
		I <sub>C</sub> = 1.0 mA, V <sub>CE</sub> = 1.0 V	70	_	-	
		I <sub>C</sub> = 10 mA, V <sub>CE</sub> = 1.0 V	100	_	300	
		$I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60	_	-	
		$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$	30	_	-	
V <sub>CE(sat)</sub>	Collector–Emitter Saturation Voltage	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 1.0 mA	_	_	0.25	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 1.0 mA	_	_	0.9	V
SMALL-SIG	SNAL CHARACTERISTICS					
f <sub>T</sub>	Current Gain-Bandwidth Product	I <sub>C</sub> = 10 mA, V <sub>CE</sub> = 20 V, f = 100 MHz	_	200	-	MHz
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 5.0 V, f = 100 kHz	_	4.5	-	pF
C <sub>ibo</sub>	Input Capacitance	V <sub>CB</sub> = 0.5 V, f = 100 kHz	_	10	_	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. All voltages (V) and currents (A) are negative polarity for PNP transistors.



0.20 C



PIN 1 **IDENTIFIER** 

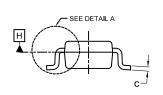
### TSOT23 6-Lead CASE 419BL **ISSUE A**

**DATE 31 AUG 2020** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
   DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
   PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25MM PER END. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
- 4. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

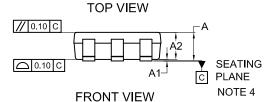
DIM L



SIDE VIEW

2,	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0.00	0.05	0.10	
A2	0.70	0.85	1.00	
А3		0.25 BSC	;	
b	0.25	0.38	0.50	
С	0.10	0.18	0.26	
D	2.80	2.95	3.10	
d	0.30 REF			
E	2.50 2.75		3.00	
E1	1.30	1.50	1.70	
е	0.95 BSC			
e1	1.90 BSC			
L1	0.60 REF			
L2	0.20	0.40	0.60	
θ	0°		10°	

MILLIMETERS



e1

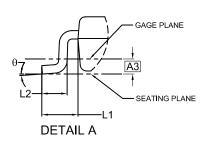
-[A]

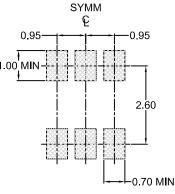
F1

-b

В

0.20 C





# LAND PATTERN RECOMMENDATION

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.





XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " • ", may or may not be present. Some products may not follow the Generic Marking.

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